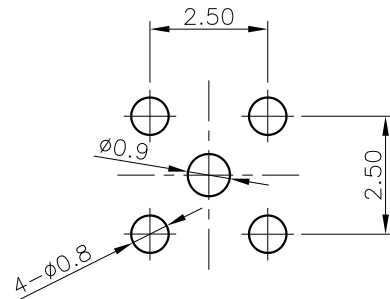
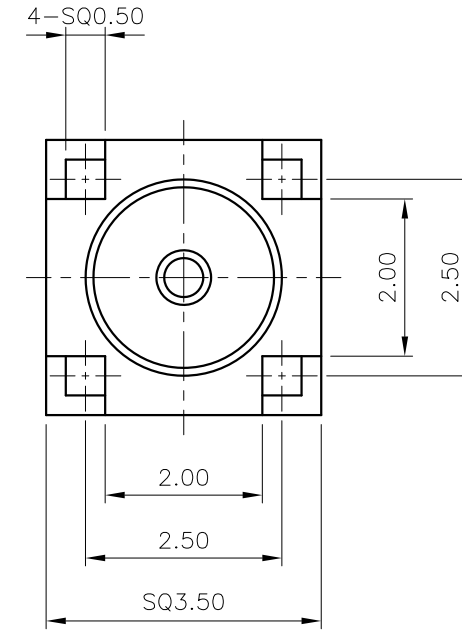
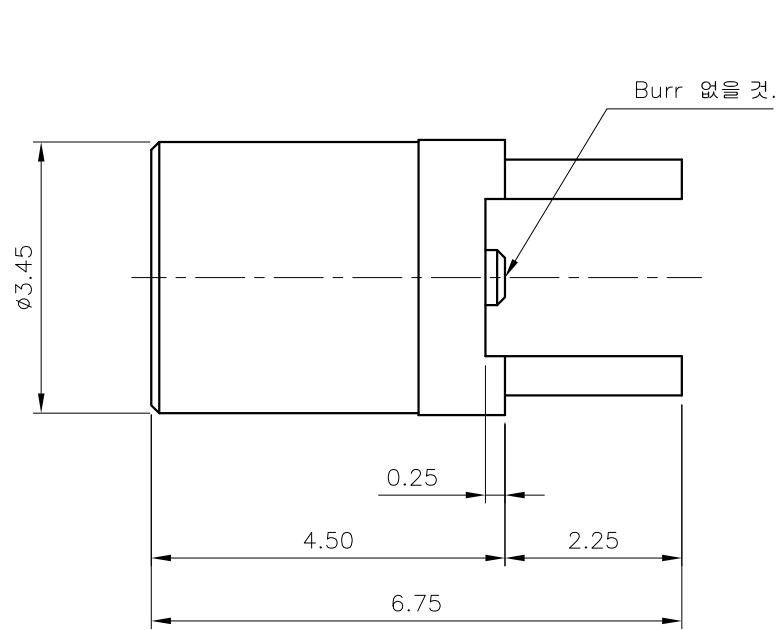


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	M.H.SONG	I.C.KIM	2013.11.01.
2	조립장 개편으로 인한 결연제 역지끼움 -> 납시베는 구조 변경	S.Y.EUN	S.H.KIM	2022.06.21.



PCB MOUNTING HOLE SIZE

3	INSULATOR	1	TEFLON		DIN00006-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02965-5/1
1	BODY	1	MBsBD	Gold Plate	DBD02135-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2013. 11. 01.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY	S.H.KIM			
MATERIAL _____		CHECKED BY	TITLE MMCX50 PCB JS-4R			
		DRAWN BY				S.Y.EUN
FINISH _____		SCALE 10/1	UNIT mm		A4	DWG NO. CN00015-7/4
						REVISION 1